

(0,80 mm) .0315"

LSEM SERIES

HIGH SPEED HERMAPHRODITIC STRIP

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?LSEM

Insulator Material:

Black Liquid Crystal Polymer Contact Material:

Phosphor Bronze

Plating: Au or Sn over 50μ" (1,27 μm) Ni Current Rating:

1.8 A per pin

(2 adjacent pins powered)
Operating Temp Range:
-55°C to +125°C

RoHS Compliant:

Processing: Lead-Free Solderable:

SMT Lead Coplanarity: (0,10 mm) .004" max Board Stacking:

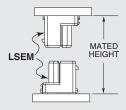
For applications requiring more than two connectors per board, contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

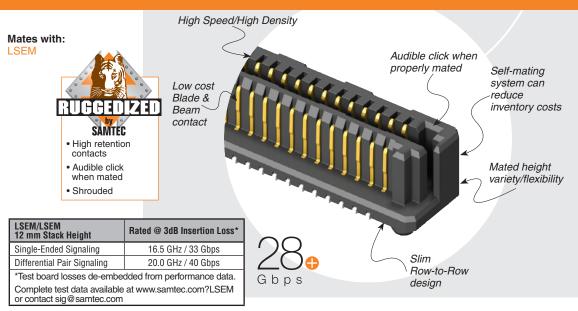


APPLICATION



LEAD STYLE	MATED HEIGHT*
-03.0 & -03.0	(6,00) .236
-03.0 & -04.0	(7,00) .276
-04.0 & -04.0	(8,00) .315
-03.0 & -06.0	(9,00) .354
-04.0 & -06.0	(10,00) .394
-06.0 & -06.0	(12,00) .472
*Processing conditions will affect mated height.	

Note: Some lengths, styles and options are non-standard, non-returnable.





20, 30, 40, 50

Specify LEAD **STYLE** from

chart

LEAD

STYLE -01

-DH only

-03.0

-04.0

-06.0

LEAD

STYLE

= Gold flash on contact. Matte Tin on tail

PLATING

OPTION

=10µ" (0,25 µm) Gold on contact Matte Tin on tail

В Α

(1,50) 4,45)

177

NA NA

.175 .059

5,45) (2,50)

.215 .098

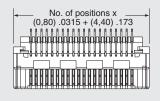
7,45) .293 (4,50)

-DV= Vertical -DH = Right Angle (Lead style -01 only)

OPTION

= (5,50 mm) .217" DIA Polyimide film Pick & Place Pad

> -TR = Tape & Reel



No. of positions x (0,80) .0315 + (1,70) .067 (1,40)	(7,80) .307 + (5,13) .202 (1,32) † .052 DIA
-DH	

